

NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIALS AND PLATING:
 - 1.1 BODY: (142-0781-821) GOLD PLATED BRASS
(142-0781-822) GOLD PLATED BRASS
 - 1.2 INSULATOR: (142-0781-821) TEFLON
(142-0781-822) TEFLON
 - 1.3 CENTER CONTACT: (142-0781-821) GOLD PLATED BERYLLIUM COPPER
(142-0781-822) GOLD PLATED BERYLLIUM COPPER
EXPOSED CENTER PIN PRE-TINNED
WITH SAC 305 SOLDER (96.5Sn/3.0Ag/.5Cu)

2. ELECTRICAL SPECIFICATIONS:
 - 2.1 IMPEDANCE: 50 OHMS
 - 2.2 FREQUENCY RANGE: 0-26.5 GHz
 - 2.3 VSWR: 1.05+.02F(GHz) MAX AT 0-18 GHz, TYPICALLY < 1.50 AT 18-26.5 GHz
 - 2.4 WORKING VOLTAGE: 170 VRMS MAX AT SEA LEVEL
 - 2.5 DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS MIN AT SEAL LEVEL
 - 2.6 INSULATION RESISTANCE: 1000 MEGOHMS MIN
 - 2.7 CONTACT RESISTANCE: CENTER CONTACT - INITIAL 3.0 MILLIOHMS MAX,
AFTER ENVIRONMENTAL - 4.0 MILLIOHMS MAX
OUTER CONDUCTOR - INITIAL 2.0 MILLIOHMS MAX
AFTER ENVIRONMENTAL - N/A
 - 2.8 CORONA LEVEL: 125 VOLTS MIN AT 70,000 FEET
 - 2.9 INSERTION LOSS: N/A (DEPENDANT UPON APPLICATION)
 - 2.10 RF HIGH POTENTIAL WITHSTANDING VOLTAGE: 335 VRMS MIN AT 4 AND 7 MHz

3. MECHANICAL SPECIFICATIONS:
 - 3.1 ENGAGEMENT/DISENGAGEMENT TORQUE: 2 INCH POUNDS MAX
 - 3.2 MATING TORQUE: 7-10 INCH POUNDS WHEN SUPPORTED WITH WRENCH
*8 INCH-POUNDS MAX UNSUPPORTED
 - 3.3 CONTACT RETENTION: 6 LBS MIN AXIAL FORCE
4 OZ-IN MIN RADIAL TORQUE
 - 3.4 DURABILITY: 500 CYCLES MIN

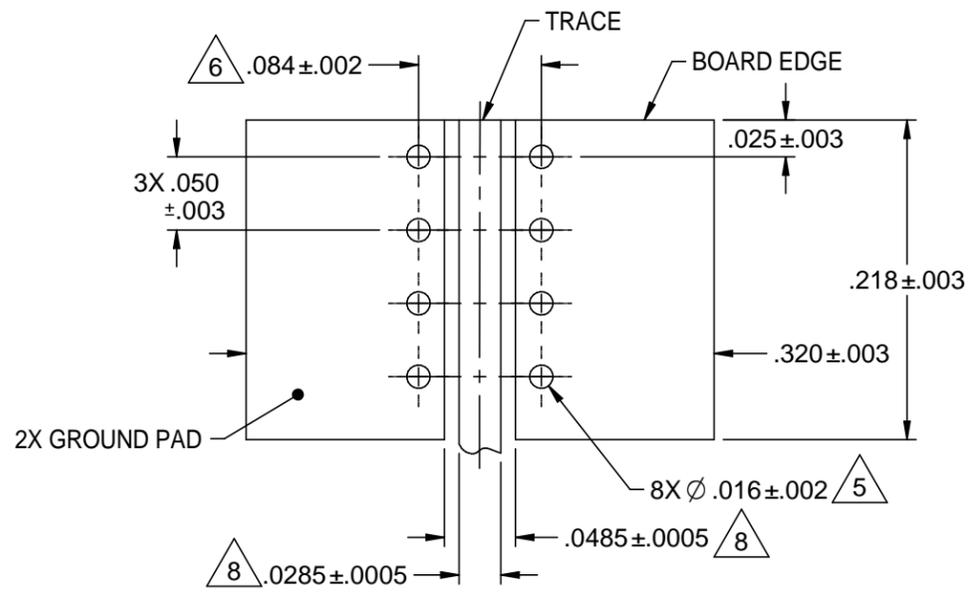
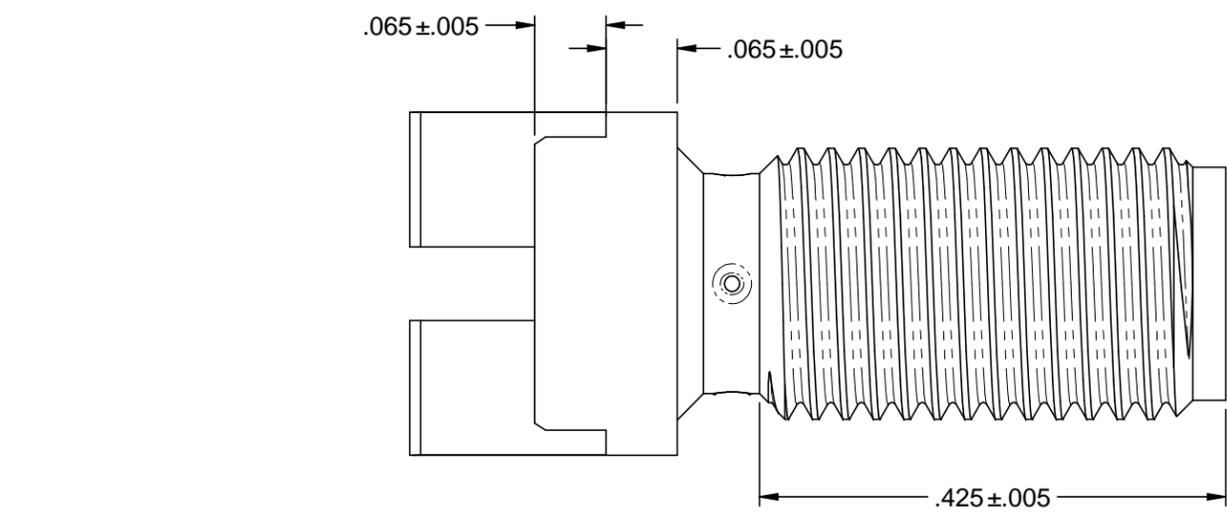
4. ENVIRONMENTAL SPECIFICATIONS:
 - 4.1 (MEETS OR EXCEEDS THE APPLICABLE PARAGRAPH OF MIL-PRF-39012)
 - 4.2 THERMAL SHOCK: MIL-STS-202, METHOD 107, CONDITION B,
4.3 EXCEPT 115°C HIGH TEMP
 - 4.4 OPERATING TEMPERATURE: -65°C TO 165°C
 - 4.5 CORROSION: MIL-STD-202, METHOD 101, CONDITION B
 - 4.6 SHOCK: MIL-STD-202, METHOD 213, CONDITION I
 - 4.7 VIBRATION: MIL-STD-202, METHOD 204, CONDITION D
 - 4.8 MOISTURE RESISTANCE: MIL-STD-202, METHOD 106

5. ALL HOLES PLATED THRU ENTIRE CIRCUIT BOARD STACKUP.

6. HOLE PATTERNS SYMMETRICAL ABOUT CENTER OF CPW TRACE.

7. FOR OPTIMUM CIRCUIT BOARD HIGH FREQUENCY PROFORMANCE:
 - A. MAINTAIN SOLID GROUND PLANE BELOW HIGH FREQUENCY SUBSTRATE.
 - B. CONTROL PULLBACK OF TRACE AND GROUND FROM BOARD EDGE.
 - C. CONTINUE GROUNDED COPLANAR LINE BEYOND GROUND PADS.
 - D. PLACE 16 MIL DIA GROUND VIAS ON BOTH SIDES OF COPLANAR WAVEGUIDE LINE AT 50 MIL INTERVALS ALONG ENTIRE LENGTH.
 - E. IMMERSION GOLD PLATE (ENIG) ALL CONDUCTORS PER IPC-4552.

8. REFERENCE DIMENSIONS FOR 50 OHM GROUNDED CPW LINE, USING ROGERS R04003, 16 MIL HIGH FREQUENCY CIRCUIT BOARD SUBSTRATE:
TRACE WIDTH - 28.5 MILS
GROUND GAPS - 10 MILS
CONDUCTOR THICKNESS - 1.4 MIL (INCLUDES PLATING)



MOUNTING FOOTPRINT
(TOP VIEW, INCLUDING TRACE DIMENSIONS)

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|---|---|--|--------------|
| | | JOHNSON | |
| | RoHS2 <input checked="" type="checkbox"/> 2011/65/EU | Title: HIGH FREQ END LAUNCH SMA BKHD JACK ASSEMBLY, EDGE MOUNT, 15 MIL PIN | |
| UNLESS OTHERWISE SPECIFIED UNITS: INCH | | Model No. 142-0781-821/830 | |
| Size B | DO NOT SCALE DRAWING | Date: 5/19/2015 | Sheet 1 of 1 |